

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended). A composition comprising one or more cross-linked and cross-linkable organosilicon polymer, wherein the composition comprises ~~comprising~~ vinyl terminated resin selected from the group consisting of vinyl functional polydimethyl siloxane and reactive polysiloxane resin having both reactive carbon-carbon double bonds and silicon-bound hydrogen atoms and one or more silicon hydrocarbon cross-linking agents ~~silicone hydrogen groups~~ and wherein the composition comprises in the range of about 1 wt % to about 80 wt % of the silicon hydrocarbon cross-linking agent.
2. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 1, wherein the vinyl functional polydimethyl siloxane is dimethylsiloxane having a vinyl group at each terminus ~~methyl-divinyl-siloxane.~~
3. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 2, wherein the methyl divinyl siloxane has a weight average molecular weight of 100,000 or greater.
4. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 1, further comprising fumed silica.
5. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 1, further comprising phenyl substituted siloxane that is vinyl functional.
6. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 5, wherein the phenyl substituted siloxane has a weight average molecular weight of 50,000 or greater.
7. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 1, wherein the polysiloxane resin comprises a silicon hydrocarbon crosslinking agent comprising alternating structures of polycyclic polyene residue and cyclic (or tetrahedral) siloxysilane residue.

8. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 1 comprising in the range of about 1 wt % to about 60 wt % of the vinyl functional polydimethyl substituted polymethyl siloxane.
9. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 8, comprising in the range of about 5 wt % to about 25 wt % of the vinyl functional polydimethyl substituted polymethyl siloxane.
10. (cancelled).
11. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 11 ~~claim 40~~, comprising in the range of about 1 wt % to about 40 wt % of the silicon hydrocarbon cross-linking agent.
12. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 1, further comprising a group VIII metal catalyst.
13. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 12, wherein the group VIII metal catalyst is selected from the group consisting of platinum based compounds, rhodium based compounds, ruthenium based compounds, iridium based compounds, palladium based compounds and mixtures thereof.
14. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 13, wherein the group VIII metal catalyst is selected from the group consisting of chloroplatinic acid, platinum chloride, dibenzonitrile platinum dichloride, platinum on carbon, platinum on silica, platinum on alumina, olefinic complexes, $\text{RhCl}(\text{PPh}_3)_3$, $\text{RhCl}(\text{CO})(\text{PPh}_3)_2$, $\text{Ru}_3(\text{CO})_{12}$, $\text{IrCl}(\text{CO})(\text{PPh}_3)_4$, $\text{Pd}(\text{PPh}_3)_4$, and mixtures thereof.
15. (currently amended). A composition ~~An organosilicon polymer~~ according to claim 1, wherein the polymer further comprises an additive selected from the group consisting of antioxidants, compatibilizing agents, metallic, mineral and organic fillers, flow control agents, air release agents, adhesion promoters, cure rate modifiers, silicone gum, rubber particles and mixtures thereof.
16. (currently amended). An electronic sensor module containing the composition ~~organosilicon polymer~~ of claim 1 as a protective encapsulant.

17. (currently amended). An electronic sensor module containing the composition ~~organosilicon~~
~~polymer~~ of claim 1 as an adhesive.